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DATICS-ICMS'09

Design, Analysis and Tools for Integrated Circuits and Systems (DATICS'09)

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Workshop in the International Conference of Mathematical Sciences

The International Conference of Mathematical Sciences 2009 (ICMS 2009) is organised by the Maltepe University, Turkey. ICMS 2009 will take place in Istanbul, Turkey, 4-10, August, 2009.

URL: <http://mathsciencesconf.maltepe.edu.tr/>

Aims and Scope

Main target of the Workshop: DATICS'09 is to bring together software/hardware engineering researchers, computer scientists, practitioners and people from industry to exchange theories, ideas,

techniques and experiences related to all areas of design, analysis and tools for integrated circuits (e.g. digital, analog and mixed-signal circuits) and systems (e.g. real-time, hybrid and embedded systems). DATICS'09 also focuses on the fields of formal methods, low power design methodologies for integrated circuits and wireless sensor networks (WSNs).

Topics

Topics of interest include, but are not limited to, the following:

- digital, analog, mixed-signal and asynchronous design
- processor, memory and RF design
- DSP and FPGA/ASIC-based design
- synthesis and physical design
- ATPG, design-for-testability and built-in self test methodologies
- embedded system hardware/software co-design and co-verification
- CAD/EDA methodologies and tools
- statistical timing analysis and low power design methodologies
- network and system on-a-chip and applications
- communication and wireless sensor networks (WSNs)
- specification languages: SystemC, SystemVerilog and UML
- theory and foundations: model checking, SAT-based methods, use of PSL, compositional methods and probabilistic methods
- applications of formal methods: equivalence checking, CSP applications and transaction-level verification
- verification methods based on hardware description/system-level languages (e.g. VHDL, SystemVerilog and SystemC)
- industrial experience reports and case studies
- real-time, hybrid and embedded systems
- all areas of modelling, simulation and verification of systems
- formalisms: process algebras, petri-nets, automaton theory and BDDs
- software engineering (including real-time Java, real-time UML and performance metrics)
- reversible computing

Industrial Collaborators and Sponsors

The workshop is partnered with:

1. CEOL: Centre for Efficiency-Oriented Languages "Towards improved software timing", University College Cork, Ireland (<http://www.ceol.ucc.ie/>)
2. International Software and Productivity Engineering Institute, USA (<http://www.intspei.com/>)
3. Intelligent Support Ltd., United Kingdom (<http://www.isupport-ltd.co.uk/>)
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This workshop is sponsored by:

1. LS Industrial Systems, South Korea (formerly LG Industrial Systems) - <http://eng.lsis.biz/>
2. Solari, Hong Kong (official sales agent of Sanyo LCD camera modules) - <http://www.solari-hk.com/>

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Paper Submissions, Proceedings and Journal Publications

- All submitted papers should be in the form of .pdf and are to be limited to a maximum length of 6 pages (A4 size, single space, Times Roman of font size 10, two columns format), including figures, tables and references.
- There is no template for the initial paper.
- Please submit full papers using the EasyChair DATICS-ICMS'09 Webpage at <http://www.easychair.org/conferences/?conf=daticsicms09>.
- If the paper(s) is/are accepted for publication, at least one of the authors of the accepted paper(s) must register to the DATICS-ICMS'09 workshop through the hosting conference ICMS'09. Details of the registration can be found at <http://mathsciencesconf.maltepe.edu.tr/node/15>
- The accepted papers in DATICS'09 will be published electronically by IJDATICS (ISSN: 2071-2987).
- All abstracts of the accepted papers in DATICS'09 will also be included in the ICMS conference proceedings (if the authors register for the ICMS'09 conference by 31 May 2009).
- Expanded and enhanced versions of accepted papers in DATICS'09 can also be considered for inclusion in one of the IAENG journals, the IIUM Engineering Journal, the IBSU Scientific Journal or the IJDATICS Journal.

DATICS Review Process

DATICS'09 consists of about 70 experts in the related fields of DATICS both from academia and industry. Each submission will be sent to at

least 2 members of the DATICS IPC and additional reviewers for review.

Important Deadlines

- Deadline for full paper submission: 15 June 2009
- Notification of acceptance: 7 July 2009
- Deadline for authors' registration: 15 July 2009

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For information, please contact ss.datics@gmail.com.

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If you are interested in joining the DATICS International Program Committee and Reviewers, please submit a brief CV by email to ss.datics@gmail.com.

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Please direct all enquiries to <mailto:ss.datics@gmail.com>

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